

### General Description

The SRE75N065FSU2D6 is a Field Stop Trench IGBT with anti-parallel diode, which offers ultra-low switching losses, high energy efficiency for switching applications such as PFC, Power Supply, Inverter, etc.

The SRE75N065FSU2D6 package is TO-247.

### Features

- High Breakdown Voltage to 650V
- Advanced Trench Fieldstop technology
  - Ultra low  $E_{off}$
  - High Ruggedness, Temperature Stability
  - Easy Parallel Switching Capability due to Positive Temperature Coefficient in  $V_{CE(SAT)}$
- Low  $V_{CE(SAT)}$
- Enhanced Avalanche Capability
- Non-Automotive Qualified

### Application

- Inverter
- Uninterruptible power supplies
- PFC application
- Converter with high switching frequency

### Symbol

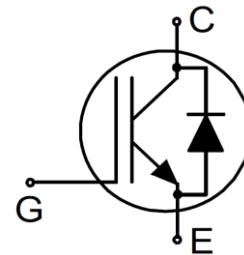
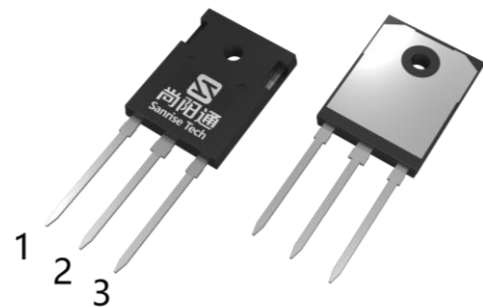


Figure 1 Symbol of SRE75N065FSU2D6

### Package Type



TO-247

- Pin 1- gate
- Pin 2&backside-collector
- Pin 3-emitter

Figure 2 Package Type of SRE75N065FSU2D6

### Ordering Information

	SRE75N065FSU2D6□□-□	
Circuit Type	_____	G: Green
Package	_____	Blank: Tube
T: TO-247		TR: Tape & Reel

Package	Part Number	Marking ID	Packing Type
TO-247	SRE75N065FSU2D6T-G2	SRE75N065FSU2D6TG2	Tube

## Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit
Collector-emitter Voltage		$V_{CES}$	650	V
Gate-emitter Voltage		$V_{GES}$	$\pm 20$	V
Transient Gate-emitter Voltage			$\pm 30$	V
Continuous Collector Current	$T_C=25^\circ\text{C}$	$I_C$	100	A
	$T_C=100^\circ\text{C}$		75	
Pulsed Collector Current, Limited by $T_{Jmax}$		$I_{CM}$	300	A
Diode Continuous Collector Current	$T_C=25^\circ\text{C}$	$I_F$	100	A
	$T_C=100^\circ\text{C}$		75	
Diode Pulsed Current, Limited by $T_{Jmax}$		$I_{FM}$	300	A
Power Dissipation	$T_C=25^\circ\text{C}$	$P_{tot}$	375	W
	$T_C=100^\circ\text{C}$		188	
Operating Junction Temperature Range		$T_J$	$-40 \sim 175^{(1)}$	$^\circ\text{C}$
Storage Temperature Range		$T_{STG}$	$-55 \sim 150$	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		$T_{LEAD}$	260	$^\circ\text{C}$

Note:

1. Reliability testing conducted at  $T_{Jmax}=175^\circ\text{C}$ .

## Thermal Resistance

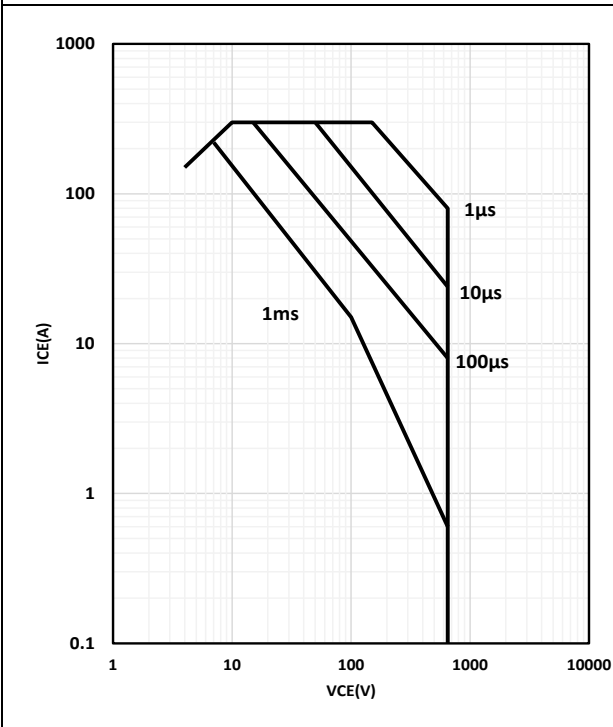
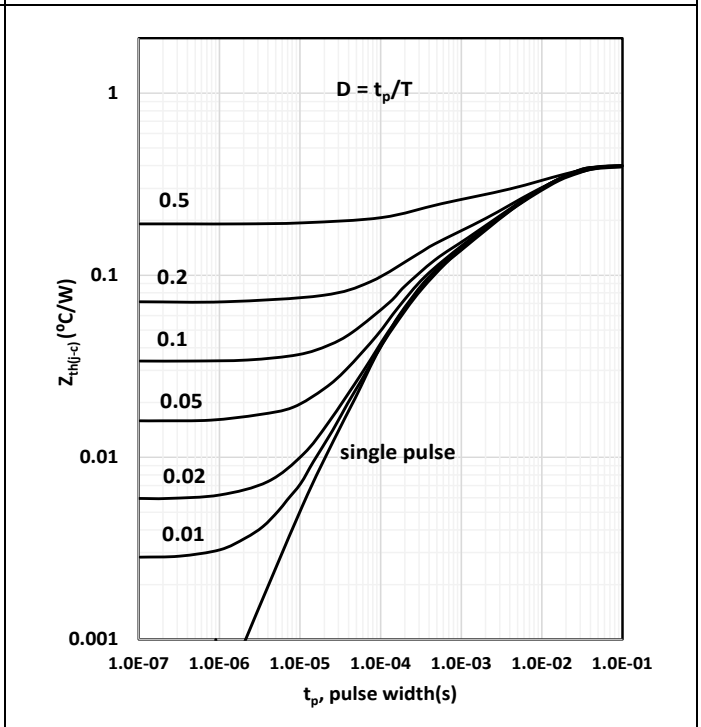
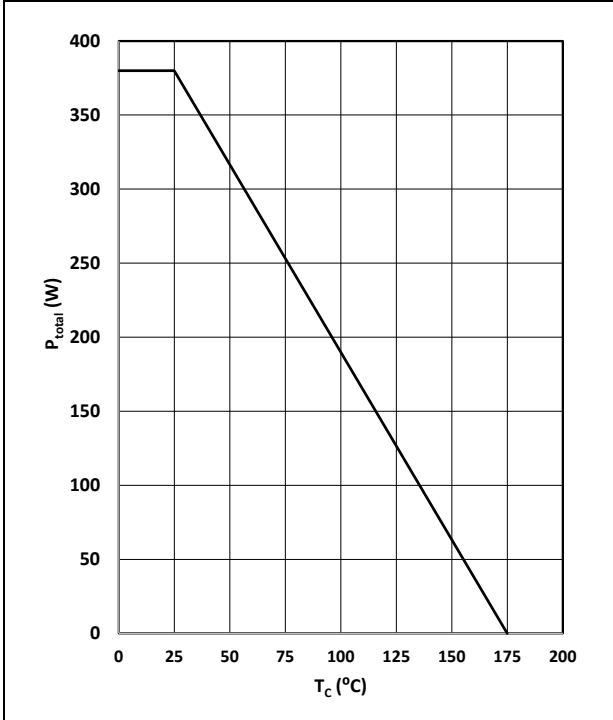
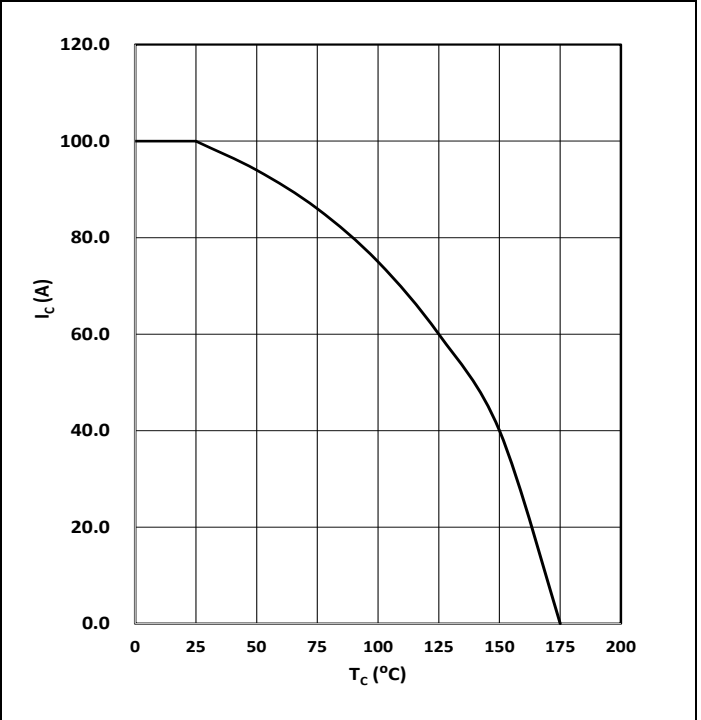
Parameter	Symbol	Min.	Typ.	Max.	Unit
IGBT Thermal Resistance, Junction-to-Case	$R_{thJC}$	-	-	0.40	$^\circ\text{C/W}$
Diode Thermal Resistance, Junction-to-Case	$R_{thJC}$	-	-	0.62	
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	-	-	40	

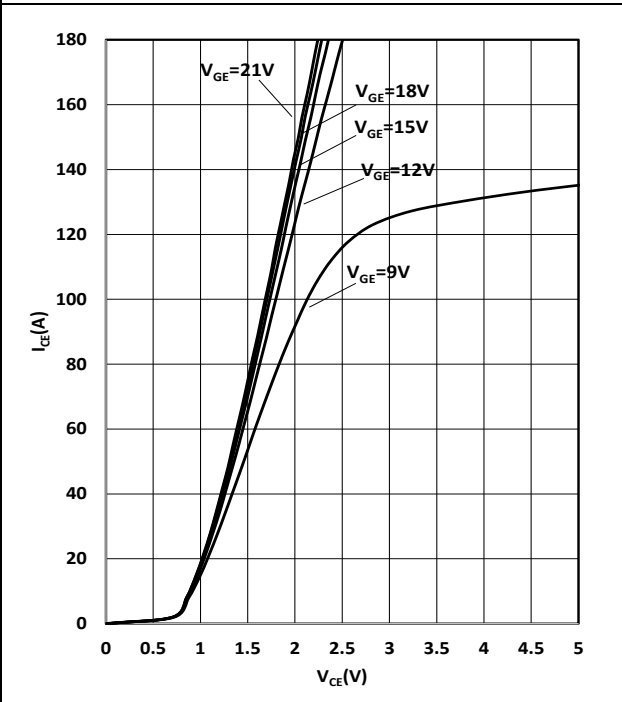
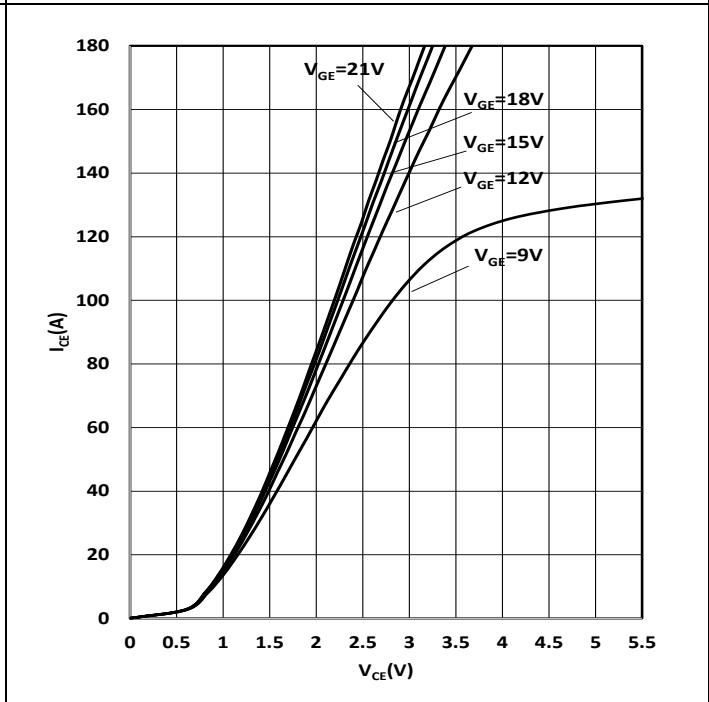
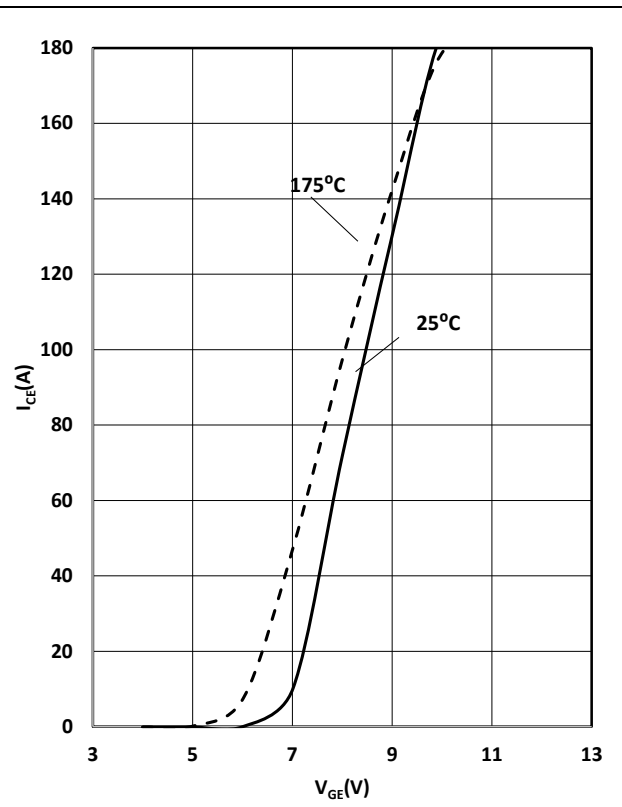
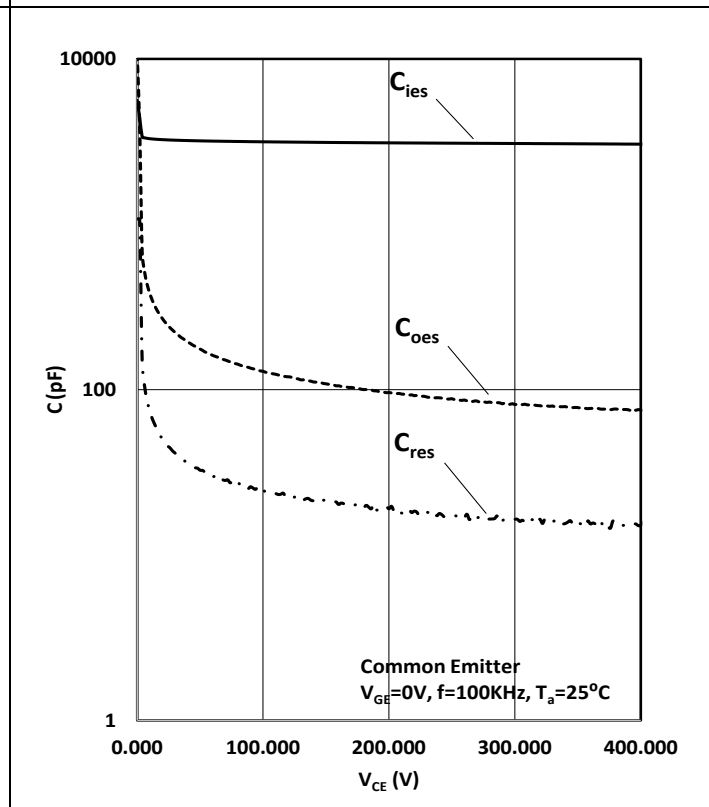
**Electrical Characteristics**
 $T_J = 25^\circ\text{C}$ , unless otherwise specified.

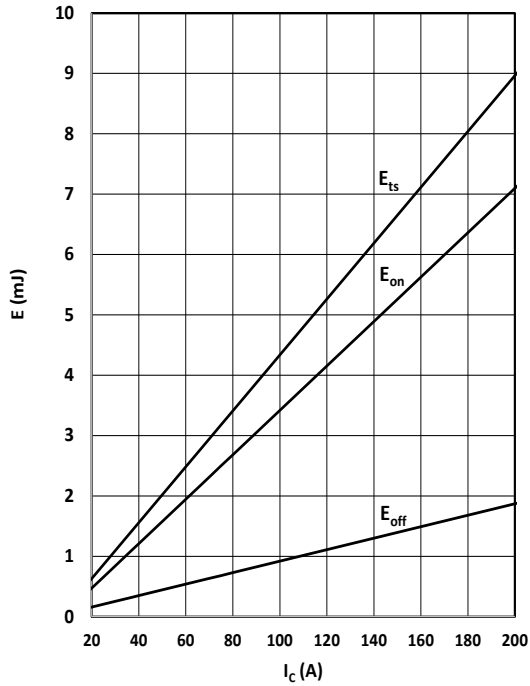
Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Statistic Characteristics</b>								
Collector-emitter Voltage	Breakdown	$BV_{CES}$	$V_{GE}=0V, I_C=250\mu A$	650			V	
Gate Threshold Voltage		$V_{GE(th)}$	$V_{CE}=V_{GE}, I_C=250\mu A$	4.6	5.1	5.8	V	
Collector-emitter saturation voltage		$V_{CESat}$	$V_{GE}=15V, I_C=75A,$ $T_J=25^\circ\text{C}$	1.40	1.48	1.70	V	
			$T_J=125^\circ\text{C}$		1.8		V	
			$T_J=150^\circ\text{C}$		1.9		V	
			$T_J=175^\circ\text{C}$		2.0		V	
Zero Gate Voltage Collector Current		$I_{CES}$	$V_{CE}=650V, V_{GE}=0V$ $T_J=25^\circ\text{C}$		0.1	40	$\mu A$	
			$T_J=175^\circ\text{C}$			1	mA	
Gate-emitter Leakage Current	Forward	$I_{GESF}$	$V_{GE}=30V, V_{CE}=0V$			100	nA	
	Reverse	$I_{GESR}$	$V_{GE}=-30V, V_{CE}=0V$			-100	nA	
<b>Dynamic Characteristics</b>								
Input Capacitance		$C_{IES}$	$V_{CE}=25V, V_{GE}=0V,$ $f=100\text{KHz}$		3234		pF	
Output Capacitance		$C_{OES}$			241			
Reverse Transfer Capacitance		$C_{RES}$			45			
Gate Resistance		$R_G$	$f=1\text{ MHz, Open Drain}$		1.7		$\Omega$	
Turn-on Delay Time		$t_{d(on)}$	$T_J=25^\circ\text{C}$ $V_{CC}=400V, I_C=75A$ $R_G=10\Omega, V_{GE}=0/15V$ Energy losses include "tail" and diode reverse recovery		34		ns	
Rise Time		$t_r$			48		ns	
Turn-off Delay Time		$t_{d(off)}$			168		ns	
Fall Time		$t_f$			32		ns	
Turn-on energy		$E_{on}$			2.5		mJ	
Turn-off energy		$E_{off}$			0.7		mJ	
Total switching energy		$E_{ts}$			3.2		mJ	
Turn-on Delay Time		$t_{d(on)}$		$T_J=175^\circ\text{C}$ $V_{CC}=400V, I_C=75A$ $R_G=10\Omega, V_{GE}=0/15V$ Energy losses include "tail" and diode reverse recovery		32		ns
Rise Time		$t_r$				63		ns
Turn-off Delay Time		$t_{d(off)}$				189		ns
Fall Time		$t_f$			41		ns	
Turn-on energy		$E_{on}$			2.84		mJ	
Turn-off energy		$E_{off}$			0.87		mJ	
Total switching energy		$E_{ts}$			3.71		mJ	
Gate to Emitter Charge		$Q_{GE}$	$V_{CC}=400V, I_C=75A$ $V_{GE}=0\text{ to }15V$			36		nC
Gate to Collector Charge		$Q_{GC}$			85			
Gate Charge Total		$Q_G$			173			

**75A 650V Trench Fieldstop IGBT with anti-parallel diode SRE75N065FSU2D6**

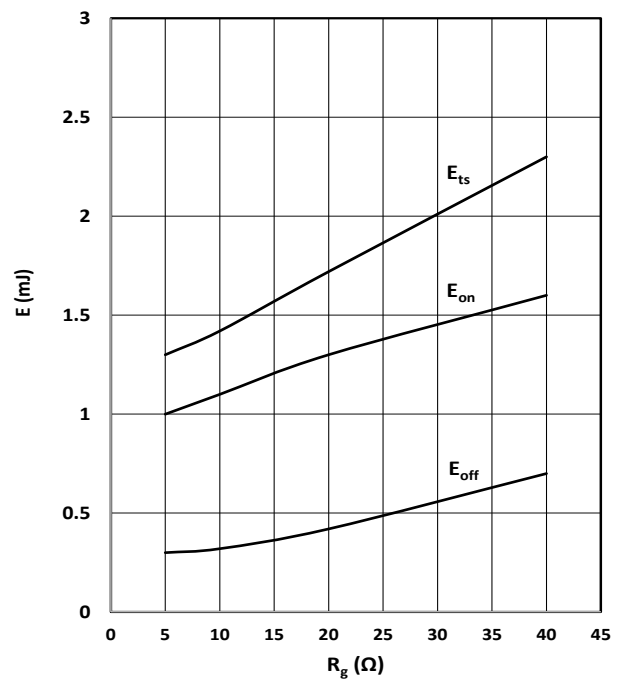
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Reverse Diode Characteristics</b>						
Diode Forward Voltage	$V_F$	$I_F=37A$ $T_J=25^{\circ}C$		1.3	1.6	V
		$I_F=37A$ $T_J=125^{\circ}C$		1.24		
		$I_F=37A$ $T_J=175^{\circ}C$		1.1		
		$I_F=75A$ $T_J=25^{\circ}C$	1.40	1.65	1.90	
		$I_F=75A$ $T_J=125^{\circ}C$		1.55		
		$I_F=75A$ $T_J=175^{\circ}C$		1.51		
Reverse Recovery Time	$t_{rr}$	$T_J=25^{\circ}C$ $V_R=400V, I_F=75A$ $dI_F/dt=920A/us$		177		ns
Reverse Recovery Charge	$Q_{rr}$			1.8		uC
Peak Reverse Recovery Current	$I_{rrm}$			30		A
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$			-540		A/ $\mu s$
Reverse Recovery Time	$t_{rr}$	$T_J=175^{\circ}C$ $V_R=400V, I_F=75A$ $dI_F/dt=940A/us$		404		ns
Reverse Recovery Charge	$Q_{rr}$			8.1		uC
Peak Reverse Recovery Current	$I_{rrm}$			64		A
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$			-240		A/ $\mu s$

**Typical Performance Characteristics**
**Figure 3: IGBT FBSOA**

 $I_C = f(V_{CE}); V_{GE} \geq 15/0V; T_j \leq 175^\circ C$ 
**Figure 4: IGBT transient thermal impedance**

 $R_{th(j-c)} = f(t_p); \text{duty cycle: } D = t_p/T$ 
**Figure 5: Power dissipation**

 $P_{tot} = f(T_c);$ 
**Figure 6: Collector current vs. temperature**

 $I_c = f(T_j); V_{GE} \geq 15V; T_j \leq 175^\circ C$

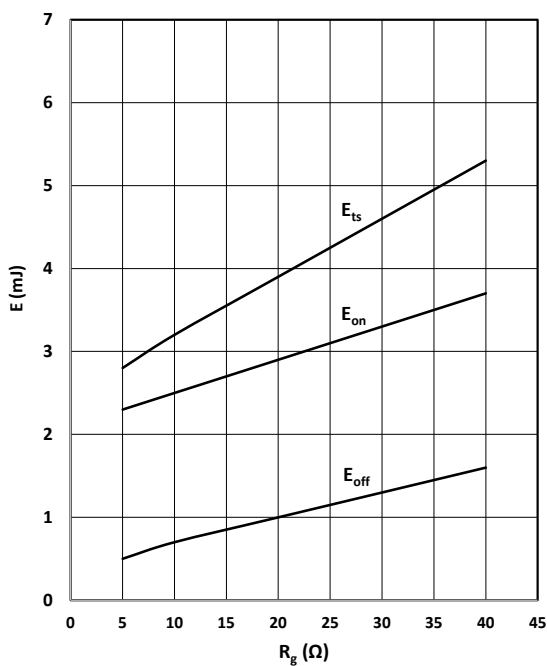
**Figure 7: Typical Output Characteristics**

 $I_C = f(V_{CE}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GE}$ 
**Figure 8: Typical Output Characteristics**

 $I_C = f(V_{CE}); T_j = 175^\circ\text{C}; \text{parameter: } V_{GE}$ 
**Figure 9: Typical transfer characteristic**

 $I_C = f(V_{CE}); T_j = 25^\circ\text{C vs } 175^\circ\text{C}$ 
**Figure 10: Typical Capacitances**

 $C = f(V_{CE}); V_{GE} = 0; f = 100\text{KHz}$

**Figure 11: Typical switching energy losses as a function of collector current**


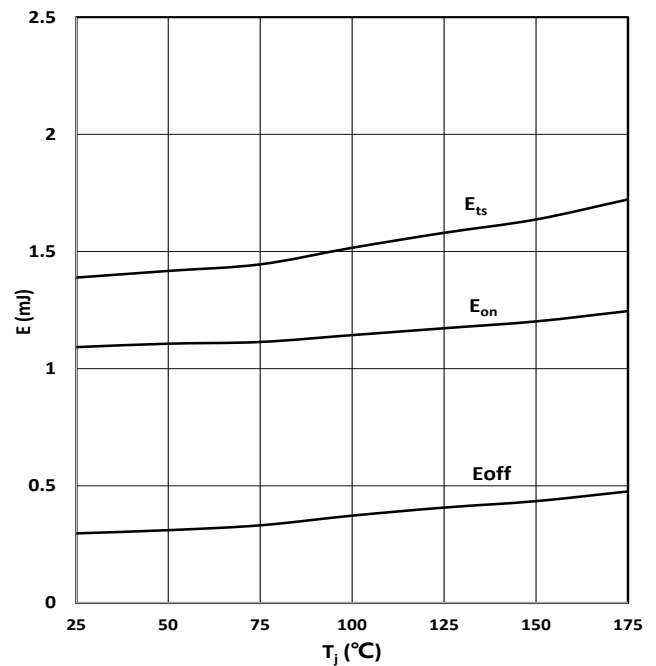
$$E=f(I_c); V_{CE}=400V; T_j=25^{\circ}C; R_G=10\Omega$$

**Figure 12: Typical switching energy losses as a function of gate resistor**


$$E=f(R_G); V_{CE}=400V; T_j=25^{\circ}C; I_c=37A$$

**Figure 13: Typical switching energy losses as a function of gate resistor**


$$E=f(R_G); V_{CE}=400V; T_j=25^{\circ}C; I_c=75A$$

**Figure 14: Typical switching energy losses as a function of junction temperature**


$$E=f(T_j); V_{CE}=400V; I_c=37A; R_G=10\Omega$$

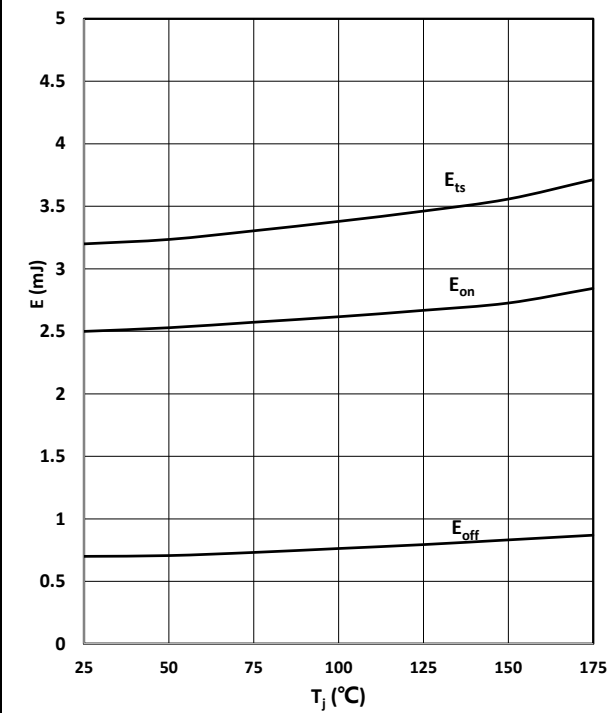
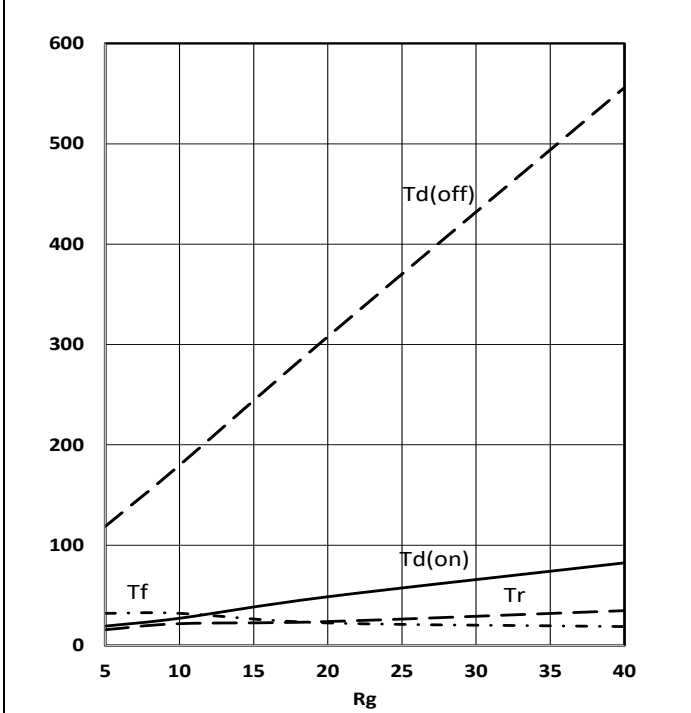
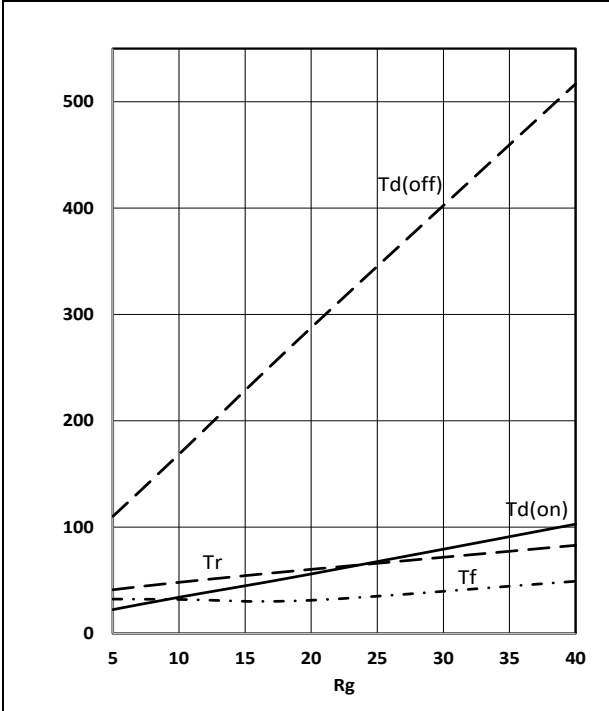
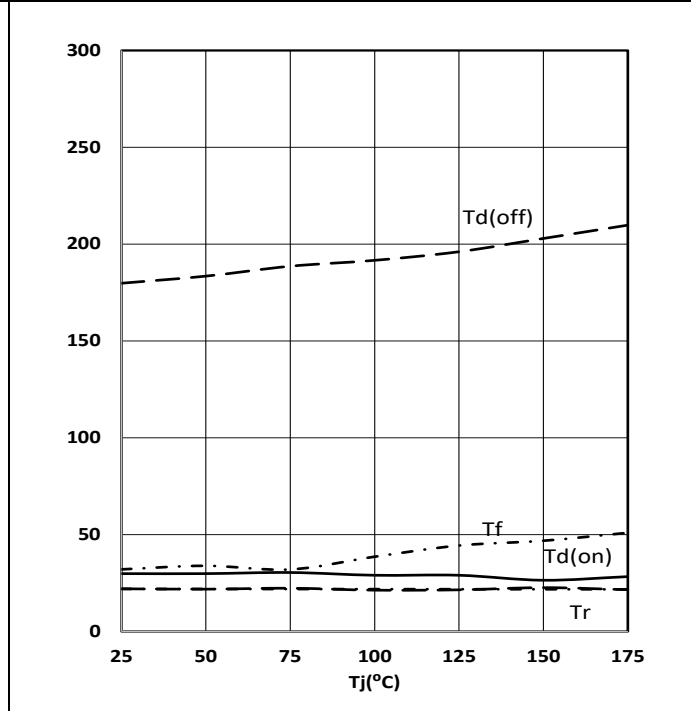
**75A 650V Trench Fieldstop IGBT with anti-parallel diode SRE75N065FSU2D6**
**Figure 15: Typical switching energy losses as a function of junction temperature**

 $E = f(T_j); V_{CE}=400V; I_C=75A; R_G=10\Omega$ 
**Figure 16: Typical Switching time as a function of gate resistor**

 $V_{CE}=400V; I_C=37A; T_j=25^\circ C$ 
**Figure 17: Typical Switching time as a function of gate resistor**

 $V_E=400V; I_C=75A; T_j=25^\circ C$ 
**Figure 18: Typical Switching time as a function of junction temperature**

 $V_{CE}=400V; I_C=37A; R_G=10\Omega$



Figure 19: Typical Switching time as a function of junction temperature

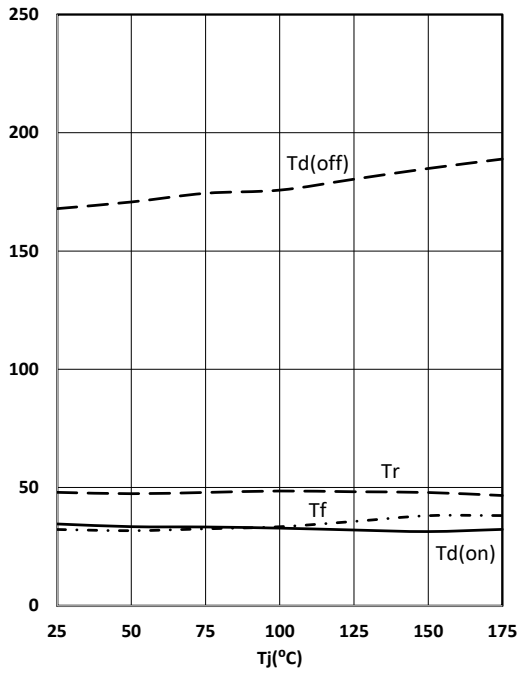

 $V_{CE}=400V; I_C=75A; R_G=10\Omega$ 

Figure 20: Typical Gate Charge

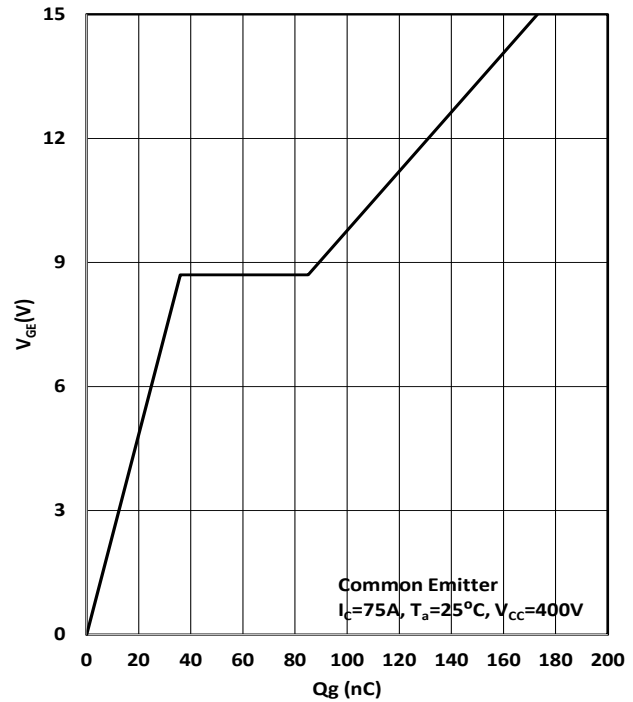

 $V_{GE}=f(Q_{gate}); I_C=75A$ 

Figure 21: Typical collector-emitter saturation voltage as a function of junction temperature

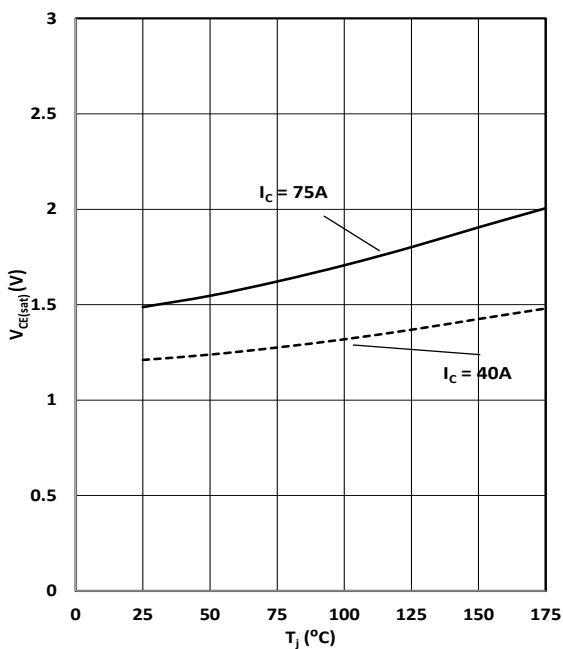

 $V_{CE}=f(T_j); V_{GE}=15V$ 

Figure 22: Gate-emitter threshold voltage as a function of junction temperature

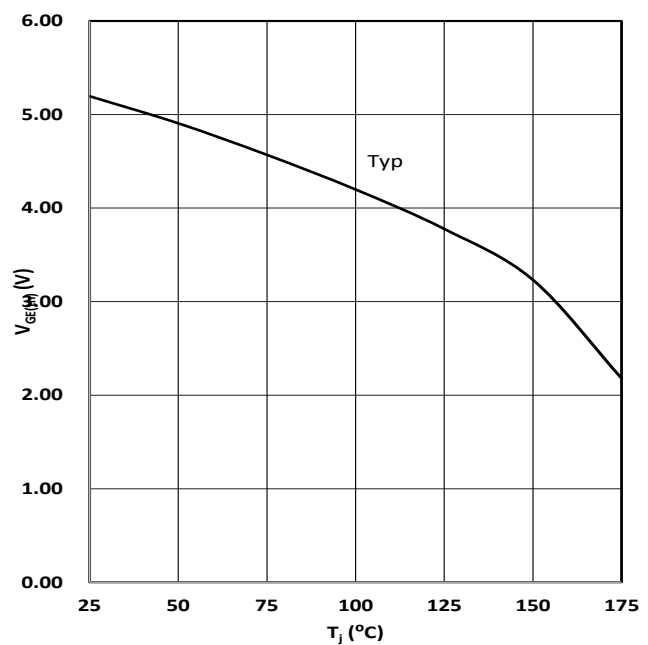
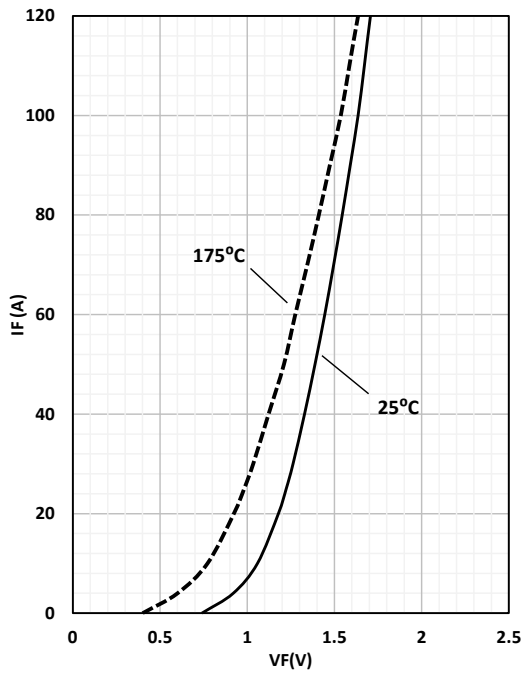
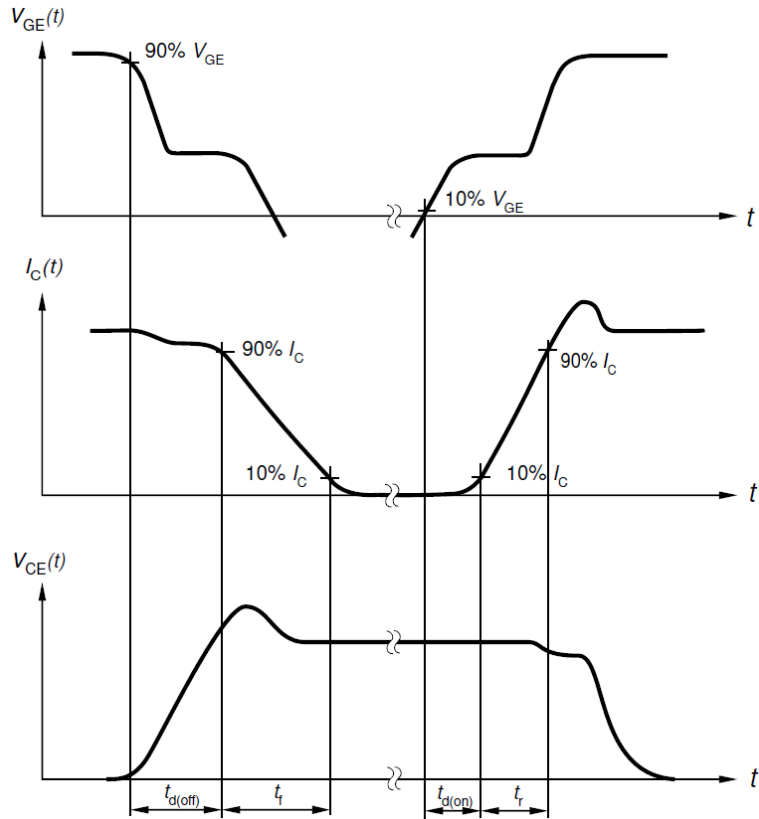
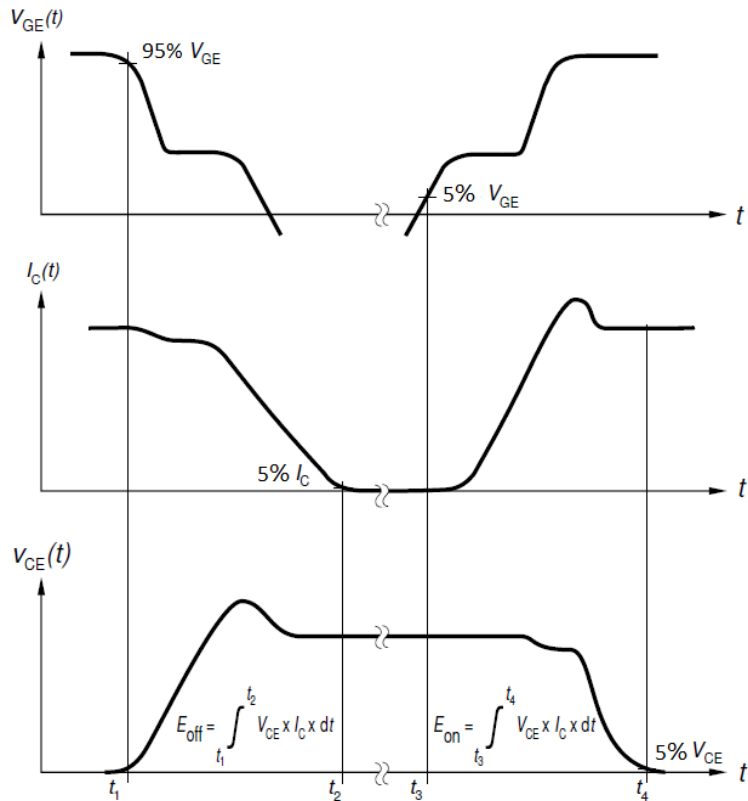

 $V_{GE}=f(T_j); I_{CE}=250\mu A$

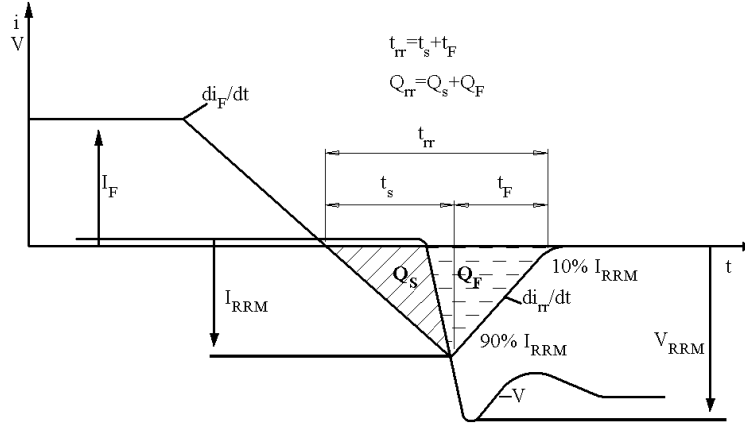
Figure 23: Typical diode forward current as a function of forward voltage



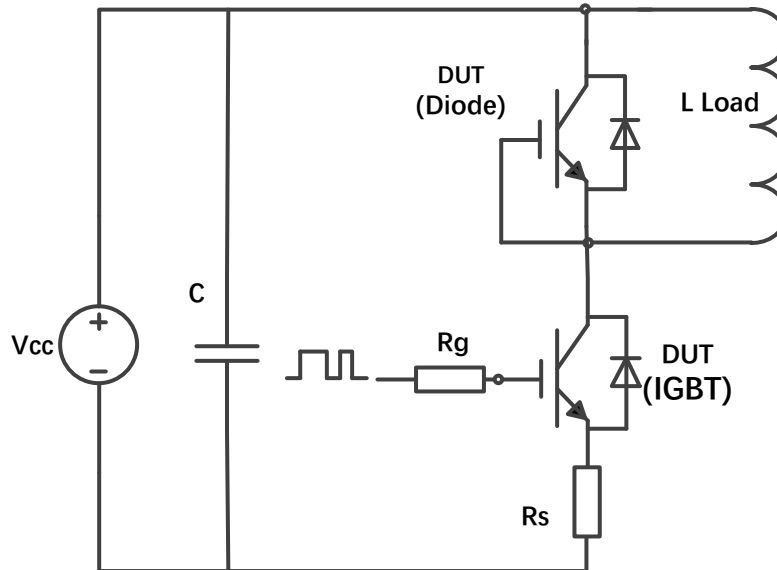
$I_F = f(V_F);$

**Test Circuits**
**1. Definition Switching times**

**2. Definition Switching losses**


**3. Definition Diode Switching Characteristics**



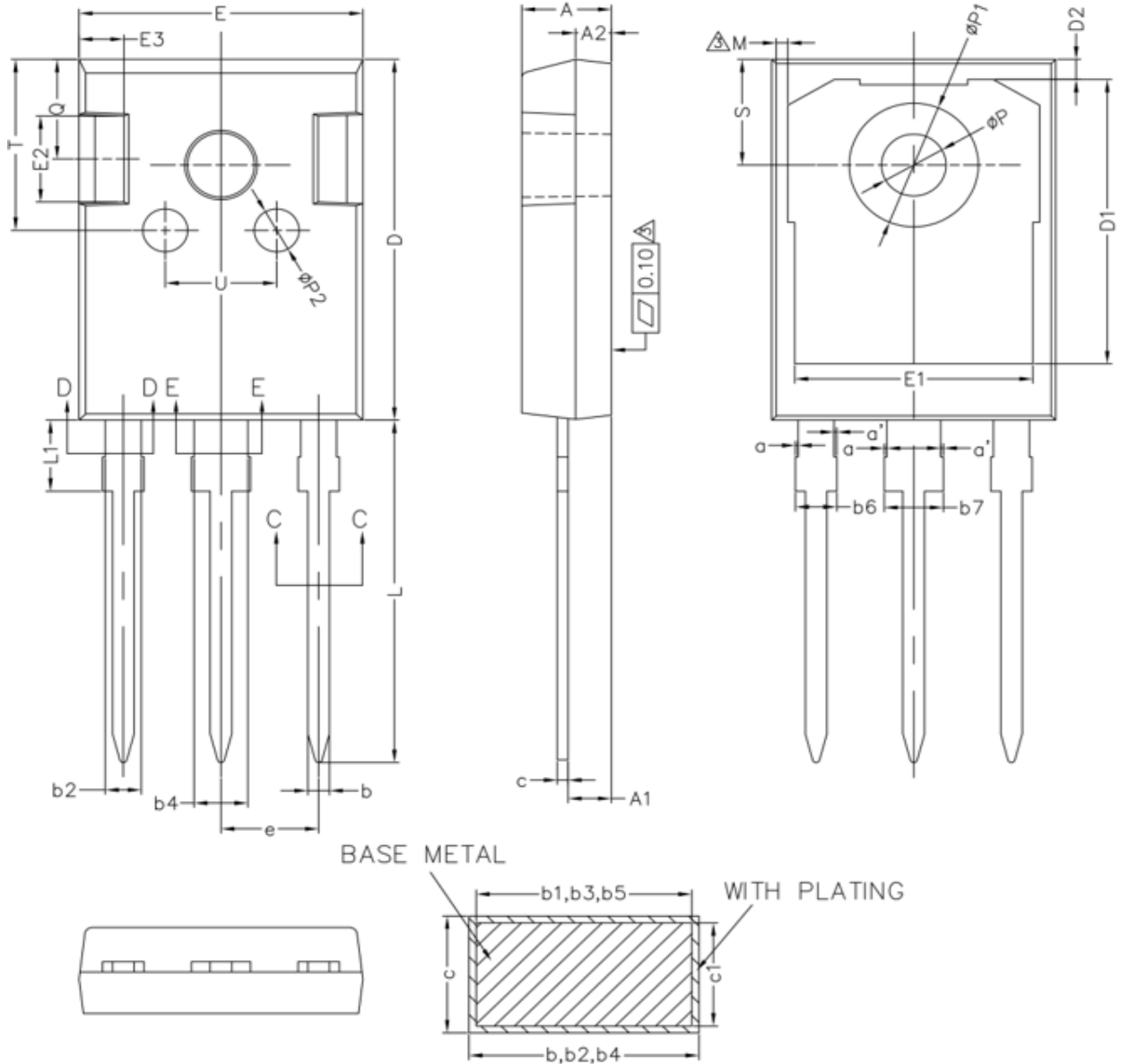
**4. Dynamic test circuit**



**Mechanical Dimensions**

**TO-247**

**Unit: mm**



**75A 650V Trench Fieldstop IGBT with anti-parallel diode SRE75N065FSU2D6**

Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.90	5.00	5.10	D2	1.05	1.20	1.35
A1	2.31	2.41	2.51	E	15.70	15.80	15.90
A2	1.90	2.00	2.10	E1	13.10	13.30	13.50
a	0	-	0.15	E2	4.90	5.00	5.10
a'	0	-	0.15	E3	2.40	2.50	2.60
b	1.16	-	1.26	e	5.34	5.44	5.54
b1	1.15	1.2	1.22	L	19.80	19.92	20.10
b2	1.96	-	2.06	L1	-	-	4.30
b3	1.95	2.00	2.02	M	0.35	-	0.95
b4	2.96	-	3.06	P	3.50	3.60	3.70
b5	2.95	3.00	3.02	P1	7.00	-	7.40
b6	-	-	2.25	P2	2.40	2.50	2.60
b7	-	-	3.25	Q	5.60	-	6.00
c	0.59	-	0.66	S	6.05	6.15	6.25
c1	0.58	0.60	0.62	T	9.80	-	10.20
D	20.90	21.00	21.10	U	6.00	-	6.40
D1	16.25	16.55	16.85	-	-	-	-



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